



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





Energy Harvesting with MB39C811-EVB-02 Evaluation Board Operation Guide

Doc. No. 002-08633 Rev. *A

Cypress Semiconductor
198 Champion Court
San Jose, CA 95134-1709
<http://www.cypress.com>

Copyrights

© Cypress Semiconductor Corporation, 2014-2016. The information contained herein is subject to change without notice. Cypress Semiconductor Corporation assumes no responsibility for the use of any circuitry other than circuitry embodied in a Cypress product. Nor does it convey or imply any license under patent or other rights. Cypress products are not warranted nor intended to be used for medical, life support, life saving, critical control or safety applications, unless pursuant to an express written agreement with Cypress. Furthermore, Cypress does not authorize its products for use as critical components in life-support systems where a malfunction or failure may reasonably be expected to result in significant injury to the user. The inclusion of Cypress products in life-support systems application implies that the manufacturer assumes all risk of such use and in doing so indemnifies Cypress against all charges.

Trademarks

All other trademarks or registered trademarks referenced herein are property of the respective corporations.

Source Code

Any Source Code (software and/or firmware) is owned by Cypress Semiconductor Corporation (Cypress) and is protected by and subject to worldwide patent protection (United States and foreign), United States copyright laws and international treaty provisions. Cypress hereby grants to licensee a personal, non-exclusive, non-transferable license to copy, use, modify, create derivative works of, and compile the Cypress Source Code and derivative works for the sole purpose of creating custom software and or firmware in support of licensee product to be used only in conjunction with a Cypress integrated circuit as specified in the applicable agreement. Any reproduction, modification, translation, compilation, or representation of this Source Code except as specified above is prohibited without the express written permission of Cypress.

Disclaimer

CYPRESS MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARD TO THIS MATERIAL, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE. Cypress reserves the right to make changes without further notice to the materials described herein. Cypress does not assume any liability arising out of the application or use of any product or circuit described herein. Cypress does not authorize its products for use as critical components in life-support systems where a malfunction or failure may reasonably be expected to result in significant injury to the user. The inclusion of Cypress' product in a life-support systems application implies that the manufacturer assumes all risk of such use and in doing so indemnifies Cypress against all charges.

Use may be limited by and subject to the applicable Cypress software license agreement.

Preface



This manual explains how to use the evaluation board. Be sure to read this manual before using the product. For this product, please consult with sales representatives or support representatives.

Handling and use

Handling and use of this product and notes regarding its safe use are described in the manuals.

Follow the instructions in the manuals to use this product.

Keep this manual at hand so that you can refer to it anytime during use of this product.

Notice on this document

All information included in this document is current as of the date it is issued. Such information is subject to change without any prior notice.


Please confirm the latest relevant information with the sales representatives.

Cautions




Caution of the products described in this document

The following precautions apply to the product described in this manual.

 WARNING	Indicates a potentially hazardous situation which could result in death or serious injury and/or a fault in the user's system if the product is not used correctly.
--	---

Electric shock, Damage	Before performing any operation described in this manual, turn off all the power supplies to the system. Performing such an operation with the power on may cause an electric shock or device fault.
Electric shock, Damage	Once the product has been turned on, do not touch any metal part of it. Doing so may cause an electric shock or device fault.

 CAUTION	Indicates the presence of a hazard that may cause a minor or moderate injury, damages to this product or devices connected to it, or may cause to lose software resources and other properties such as data, if the device is not used appropriately.
--	---

Cuts, Damage	Before moving the product, be sure to turn off all the power supplies and unplug the cables. Watch your step when carrying the product. Do not use the product in an unstable location such as a place exposed to strong vibration or a sloping surface. Doing so may cause the product to fall, resulting in an injury or fault.
Cuts	The product contains sharp edges that are left unavoidably exposed, such as jumper plugs. Handle the product with due care not to get injured with such pointed parts.
Damage	Do not place anything on the product or expose the product to physical shocks. Do not carry the product after the power has been turned on. Doing so may cause a malfunction due to overloading or shock.
Damage	Since the product contains many electronic components, keep it away from direct sunlight, high temperature, and high humidity to prevent condensation. Do not use or store the product where it is exposed to much dust or a strong magnetic or electric field for an extended period of time. Inappropriate operating or storage environments may cause a fault.
Damage	Use the product within the ranges given in the specifications. Operation over the specified ranges may cause a fault.
Damage	To prevent electrostatic breakdown, do not let your finger or other object come into contact with the metal parts of any of the connectors. Before handling the product, touch a metal object (such as a door knob) to discharge any static electricity from your body.

Damage	When turning the power on or off, follow the relevant procedure as described in this document. Before turning the power on, in particular, be sure to finish making all the required connections. Furthermore, be sure to configure and use the product by following the instructions given in this document. Using the product incorrectly or inappropriately may cause a fault.
Damage	Always turn the power off before connecting or disconnecting any cables from the product. When unplugging a cable, unplug the cable by holding the connector part without pulling on the cable itself. Pulling the cable itself or bending it may expose or disconnect the cable core, resulting in a fault.
Damage	Because the product has no casing, it is recommended that it be stored in the original packaging. Transporting the product may cause a damage or fault. Therefore, keep the packaging materials and use them when re-shipping the product.

Contents



1. Evaluation Board Specification	7
1.1 Description	7
1.2 Evaluation Board Specification	7
2. Block Diagram	8
3. PIN Descriptions	9
3.1 Input/Output Pin Descriptions	9
3.2 Jumper, Switch descriptions	10
4. Setup and Verification	11
4.1 Solar (or Light) Energy Harvesting 1.....	11
4.2 Solar (or Light) Energy Harvesting 2.....	12
4.3 Vibration Energy Harvesting	13
5. Component and Wiring Layout	15
5.1 Component Layout	15
5.2 Wiring Layout.....	16
6. Circuit Schematic	19
7. Component List	20
8. Evaluation Board Picture	23
9. Ordering Information	25
Revision History	26
Document Revision History	26

1. Evaluation Board Specification



1.1 Description

The MB39C811-EVB-02 is the evaluation board for the energy harvesting IC, MB39C811. This evaluation board is capable of accepting solar, piezoelectric, or any high impedance AC or DC source.

1.2 Evaluation Board Specification

Table 1-1. Evaluation board specification

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Input voltage	VIN	-	2.6	-	18	V
Input slew rate	VIN	VIN \geq 7V	-	-	0.25	V/ms
Input current	VIN	-	-	-	100	mA
AC pin input voltage	AC1-1,AC1-2, AC2-1,AC2-2	-	-	-	18	V
AC pin input current	AC1-1,AC1-2, AC2-1,AC2-2	-	-	-	50	mA
Output voltage	VOUT	See Table4-3	1.5	-	5	V
Output current	VOUT	Up to 100mA	-	-	100	mA
UVLO release voltage	VOUT	SW002=L, SW000=L, SW001=L	3.8	4.0	4.2	V
		SW002=L, SW000=L, SW001=H				
		SW002=L, SW000=H, SW001=L				
		SW002=L, SW000=H, SW001=H	4.94	5.2	5.46	V
		SW002=H, SW000=L, SW001=L				
		SW002=H, SW000=L, SW001=H	6.84	7.2	7.56	V
		SW002=H, SW000=H, SW001=L				
SW002=H, SW000=H, SW001=H						
Forward bias voltage	AC1-1,AC1-2, AC2-1,AC2-2	IF=10uA	150	280	450	mV

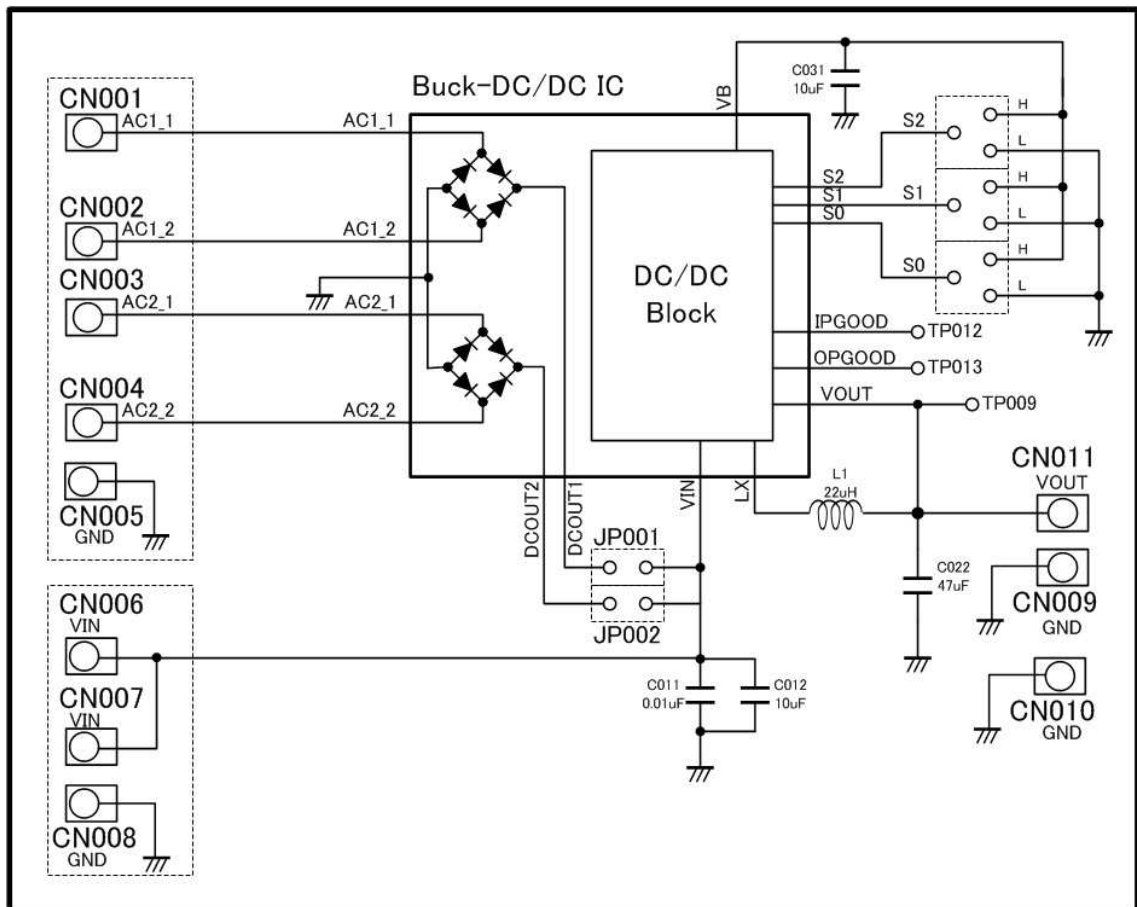
Please see the MB39C811 datasheet (DS405-00013) for more information.

Board size : 80mm x80mm

2. Block Diagram



Figure 2-1. Block diagram



3. PIN Descriptions



3.1 Input/output Pin Descriptions

Table 3-1. Input/output pin descriptions

Pin number	Pin symbol	I/O	Function description
CN001	AC1-1	I	Bridge rectifier 1, AC input 1
CN002	AC1-2	I	Bridge rectifier 1 , AC input 2
CN003	AC2-1	I	Bridge rectifier 2 , AC input 1
CN004	AC2-2	I	Bridge rectifier 2 , AC input 2
CN005	GND	-	GND pin
CN006	VIN	I	DC power input It supplies power directly to the VIN pin, and not through the bridge rectifier.
CN007	VIN	I	
CN008	GND	-	GND pin
CN009	GND	-	GND pin
CN010	GND	-	GND pin
CN011	VOUT	O	VOUT pin
TP005	DCOUT1	O	Bridge rectifier 1, DC monitor pin
TP006	DCOUT2	O	Bridge rectifier 2, DC monitor pins
TP009, TP020	VOUT	O	VOUT monitor pin
TP010	VB	O	VB voltage monitor pin
TP012	IPGOOD	O	Input power good pin
TP013	OPGOOD	O	Output power good pin
TP014~TP019,TP023	GND	-	GND pin
J001	unnecessary	O	AC1-1,AC1-2,AC2-1,AC2-2 monitor pins
J002	unnecessary	O	VOUT, IPGOOD, OPGOOD monitor pins
J003	unused	-	-

3.2 Jumper, Switch descriptions

Table 3-2. Jumper, Switch Descriptions

Jumper, Switch	Function description	Initial setting
JP001 (*1) : EVB back side	Connection jumper between the DC output pin (DCOUT1) of bridge rectifier 1 and DC input pin (VIN) of DC/DC converter to "open/short"	Open
JP002 (*1) : EVB back side	Connection jumper between the DC output pin (DCOUT2) of bridge rectifier 2 and DC input pin (VIN) of DC/DC converter to "open/short"	Open
JP003	Short between AC1-1 lines	Short
JP004	Short between AC1-2 lines	Short
JP005	Short between AC2-1 lines	Short
JP006	Short between AC2-2 lines	Short
JP007	Short between S0 pin and toggle switch	Short
JP008	Short between S1 pin and toggle switch	Short
JP009	Short between S2 pin and toggle switch	Short
JP010 : EVB back side	Short between VOUT and zener diode. VOUT protection (unnecessary)	Short
JP011	Short between VB and zener diode. VB protection (unnecessary)	Short
JP012	Short between LX lines	Short
SW000	High/Low selecting switch for S0. See Table 3-3	L
SW001	High/Low selecting switch for S1. See Table 3-3	L
SW002	High/Low selecting switch for S2. See Table 3-3.	L

*1: Open/Short by soldering

Table 3-3. Output Voltage Settings

S2 pin (SW002)	S1 pin (SW001)	S0 pin (SW000)	Preset output voltage
L	L	L	1.5 (Initial setting)
L	L	H	1.8
L	H	L	2.5
L	H	H	3.3
H	L	L	3.6
H	L	H	4.1
H	L	L	4.5
H	H	H	5.0

4. Setup and Verification



4.1 Solar (or Light) Energy Harvesting 1

1. Set the switches (SW000=L, SW001=L, SW002=L) as shown in the Figure 4-1(see the Table 3-2 for the initial settings).
2. Input 4.0V or more to CN006 or CN007 (VIN). The UVLO release voltage is required to start up (see the Table 1-1).
3. 1.5V is output to CN011 (VOUT).
4. To change the output voltage, change the switch settings (see the Table 3-3)

Figure 4-1. Solar (or light) energy harvesting 1

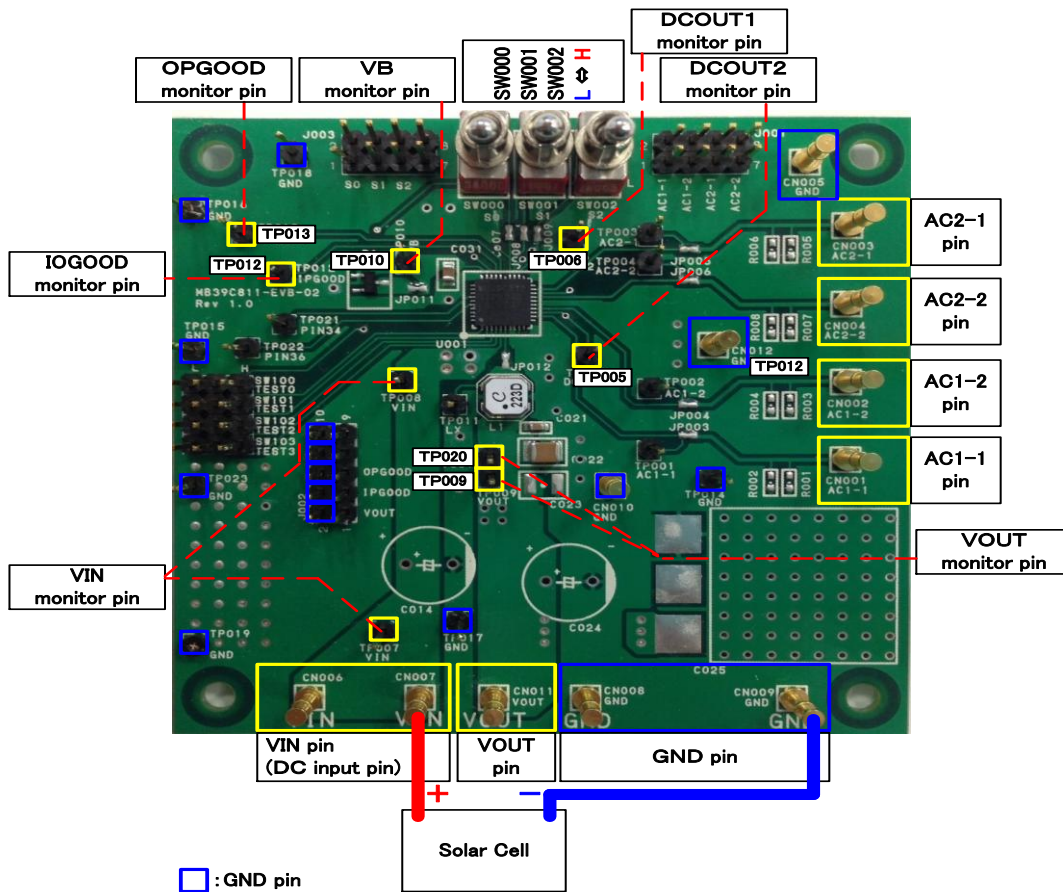
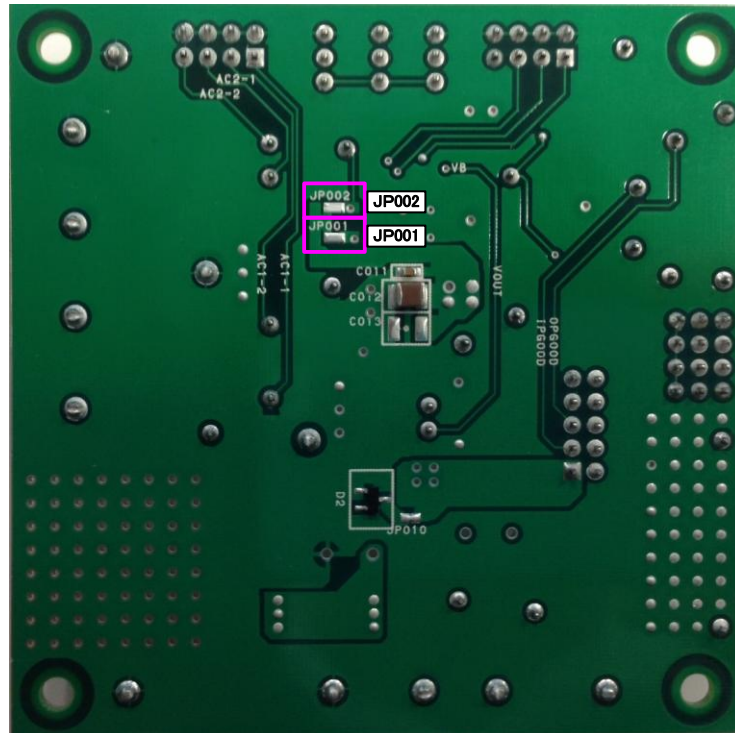


Figure 4-3. Jumper's connection between the bridge rectifier's output pins (DCOUT) and input pin (VIN)



:When using the bridge rectifiers, Solder JP001、JP002 showed in this figure.

4.3 Vibration Energy Harvesting

1. Set the switches (SW000=L, SW001=L, SW002=L) as shown in the Figure 5-1 (see the Table 3-2 for the initial settings).
2. Connect the each jumper's land pattern (JP001 and JP002) by soldering as shown in the Figure 5-3.
3. Input AC voltages into CN001 and CN002 (AC1-1 and AC1-2) to make the VIN monitor pin 4V or more. The UVLO release voltage is required to start up (see the Table 1-1). Also, please consider the forward voltage drop because of the use of diodes (see the Table 1-1).
4. 1.5V is output to CN011 (VOUT).
5. To change the output voltage, change the switch settings (see the Table 3-3).

Figure 4-4. Vibration energy harvesting

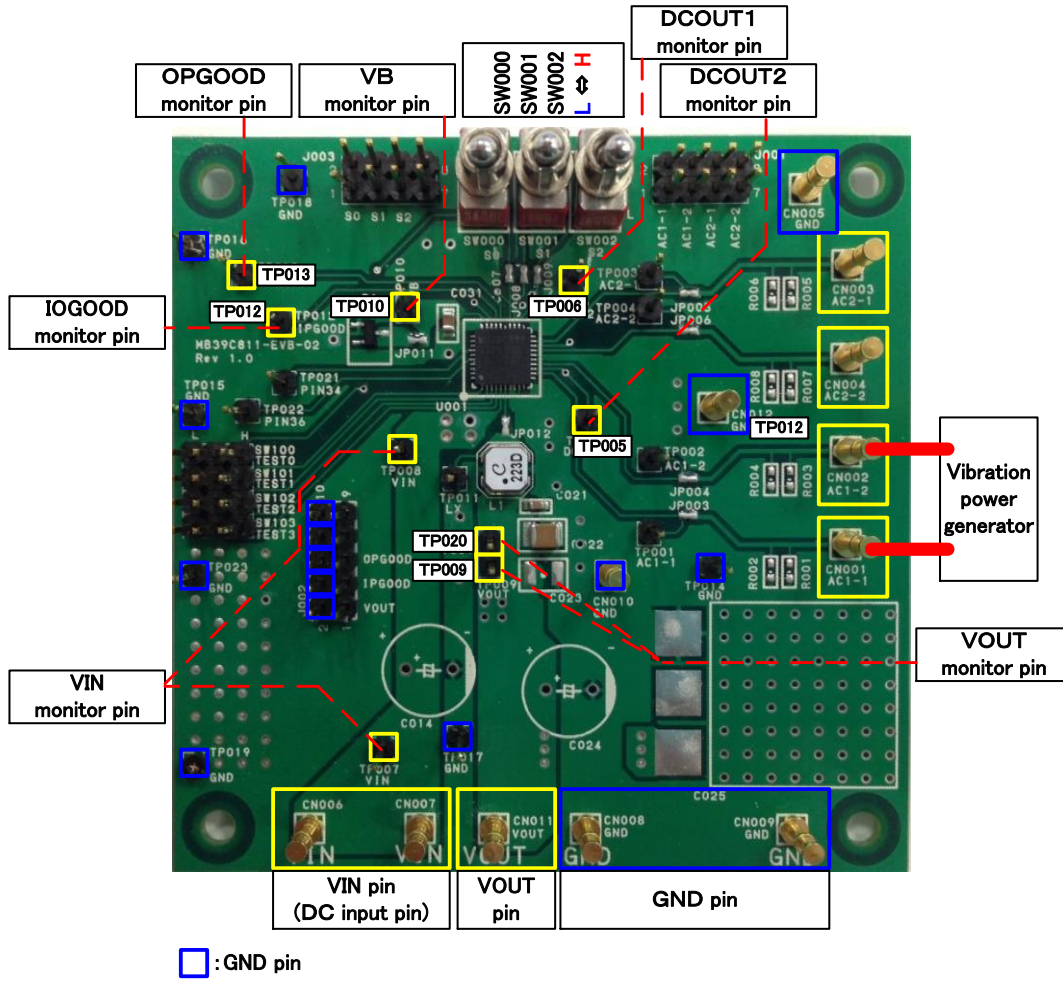
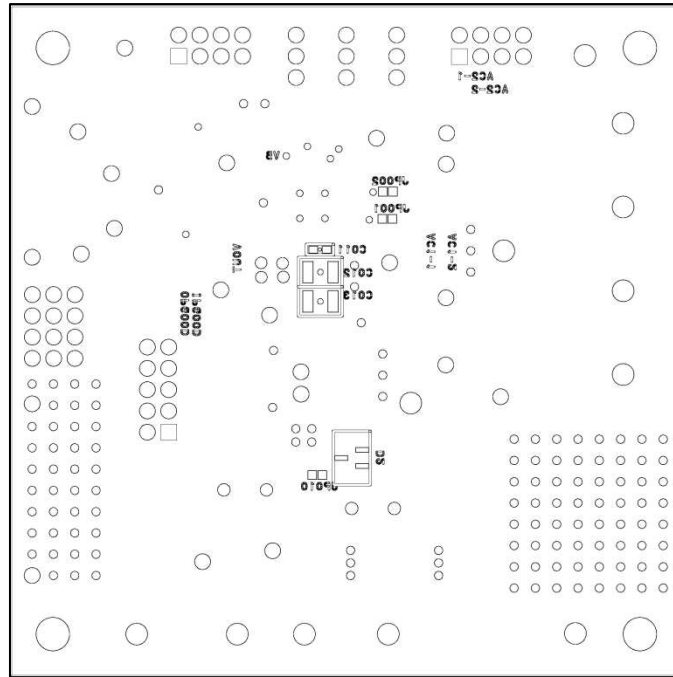


Figure 5-2. Component layout (layer 4)



5.2 Wiring Layout

Figure 5-3. Wiring layout (layer 1)

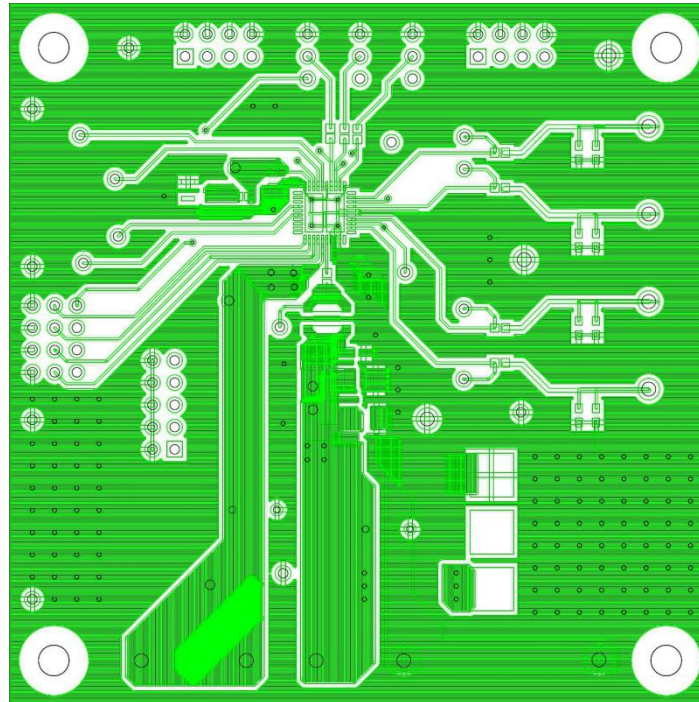


Figure 5-4. Wiring layout (layer 2)

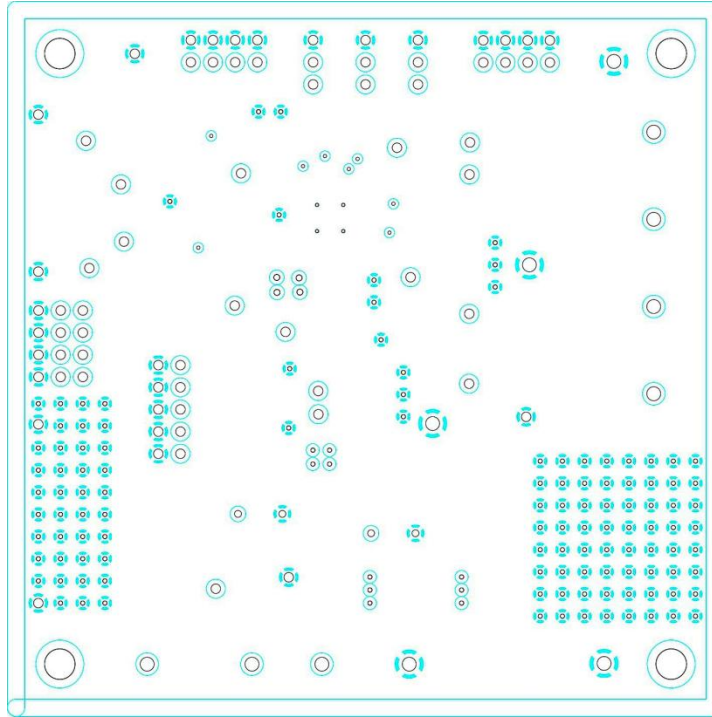


Figure 5-5. Wiring layout (layer 3)

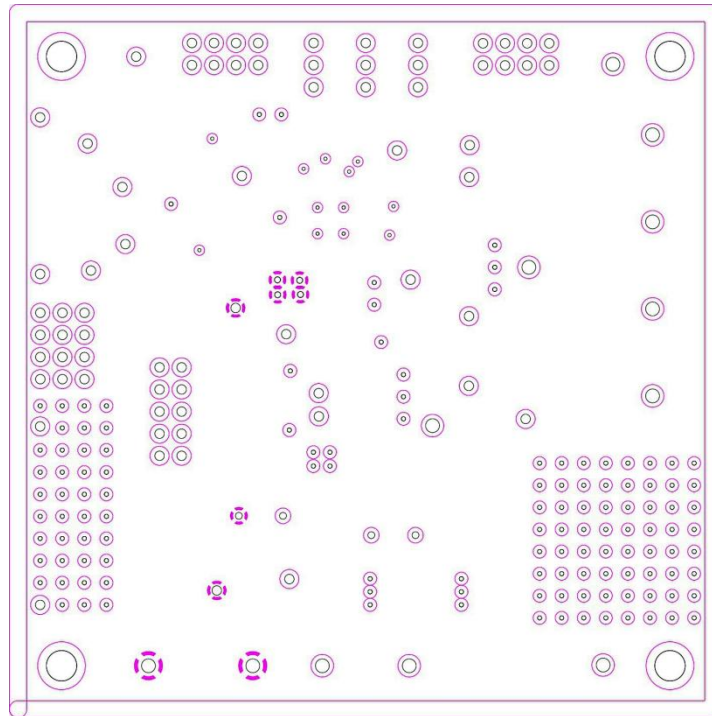
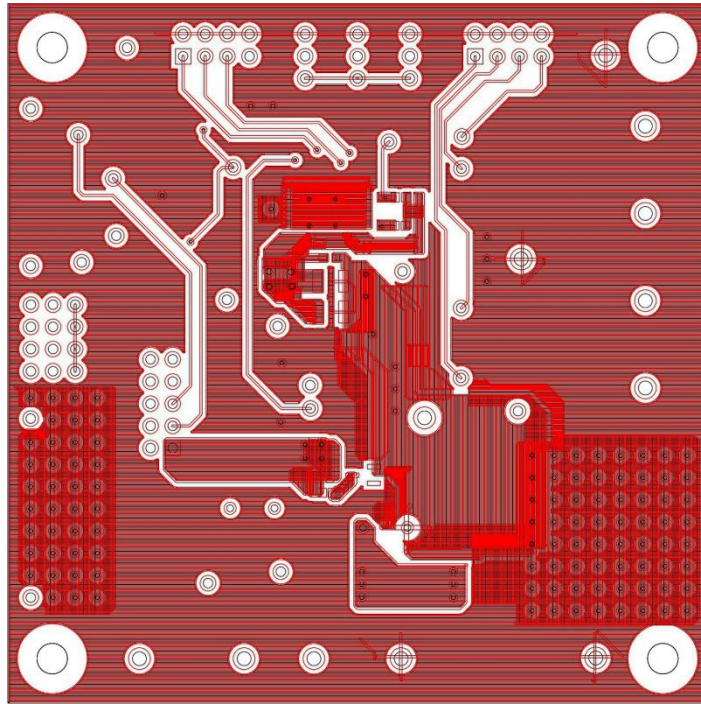


Figure 5-6. Wiring layout (layer 4)



6. Circuit Schematic

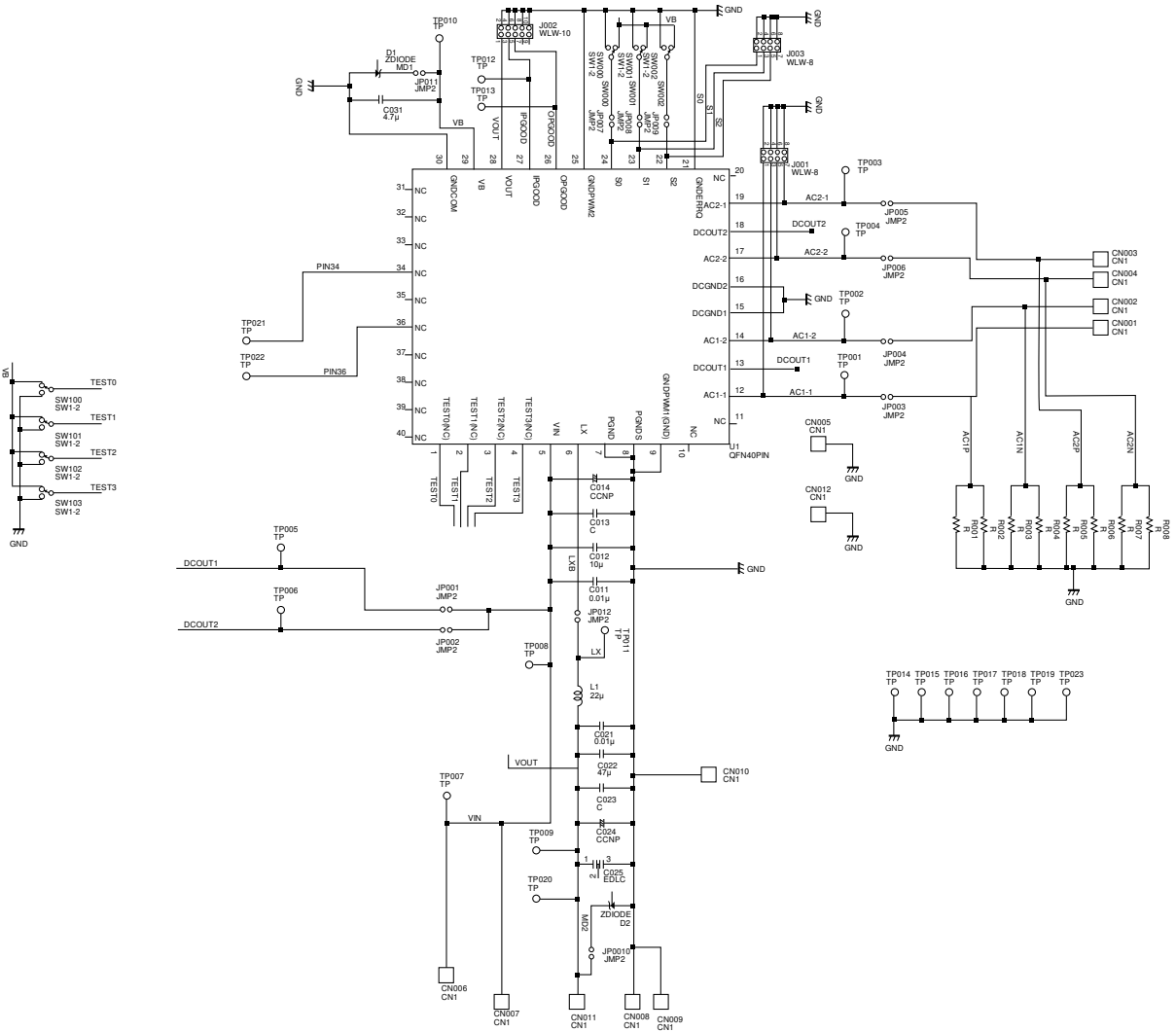


Figure 6-1. Circuit Schematic

7. Component List



Table 7-1. Component list

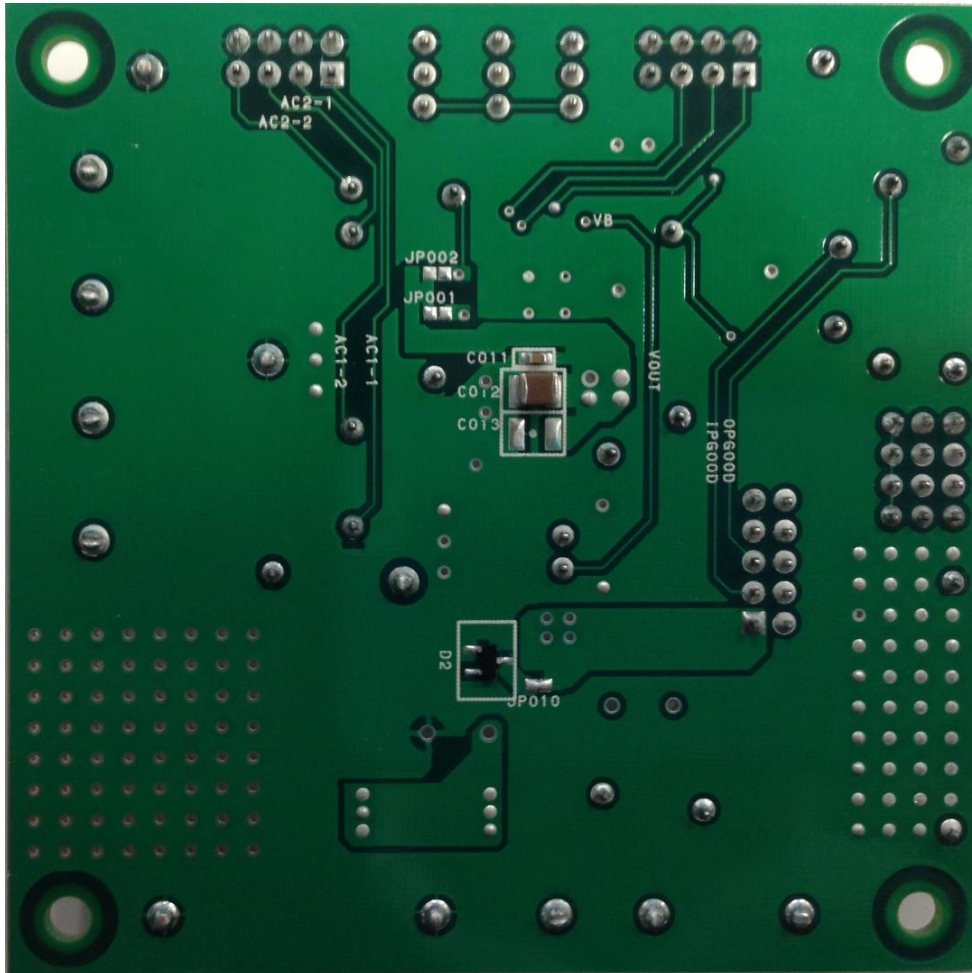
No.	Component number	Non-mounted	Vender	Part number	Rating	Note
1	C011		murata	GRM188R71H103K A01D	50V	
2	C021		murata	GRM188R71H103K A01D	50V	
3	C012		murata	GRM32ER71H106K A12L	50V	
4	L1		COILCR AFT	LPS5030-223ML	-	4.9 x 4.9 mm footprint; less than 3 mm tall
5	C031		murata	GRM21BR71C475K A73L	16V	
6	C022		murata	GRM32ER71A476K E15L	10V	
7	C013	N.M.			-	Surface Mount Device (SMD): 3225
8	C023	N.M.			-	Surface Mount Device (SMD): 3225
9	C014	N.M.			-	Insertion Mount Device (IMD): 5.08mm
10	C024	N.M.			-	Insertion Mount Device (IMD): 5.08mm
11	CN001		mac8	WT-2-1	-	
12	CN002		mac8	WT-2-1	-	
13	CN003		mac8	WT-2-1	-	
14	CN004		mac8	WT-2-1	-	
15	CN005		mac8	WT-2-1	-	
16	CN006		mac8	WT-2-1	-	
17	CN007		mac8	WT-2-1	-	
18	CN008		mac8	WT-2-1	-	
19	CN009		mac8	WT-2-1	-	
20	CN010		mac8	WT-2-1	-	
21	CN011		mac8	WT-2-1	-	

No.	Component number	Non-mounted	Vender	Part number	Rating	Note
22	CN012		mac8	WT-2-1	-	
23	C025	N.M.	TDK	EDLC272020-501-2F	-	
24	JP001	N.M.			-	There are 1608 size lands on the EVB. They can be connected by soldering.
25	JP002	N.M.			-	There are 1608 size lands on the EVB. They can be connected by soldering.
26	JP003		-	-	-	The 1608 size lands on the EVB are connected by soldering.
27	JP004		-	-	-	The 1608 size lands on the EVB are connected by soldering.
28	JP005		-	-	-	The 1608 size lands on the EVB are connected by soldering.
29	JP006		-	-	-	The 1608 size lands on the EVB are connected by soldering.
30	JP007		-	-	-	The 1608 size lands on the EVB are connected by soldering.
31	JP008		-	-	-	The 1608 size lands on the EVB are connected by soldering.
32	JP009		-	-	-	The 1608 size lands on the EVB are connected by soldering.
33	JP010		-	-	-	The 1608 size lands on the EVB are connected by soldering.
34	JP011		-	-	-	The 1608 size lands on the EVB are connected by soldering.
35	JP012		-	-	-	The 1608 size lands on the EVB are connected by soldering.
36	U1		Cypress	MB39C811(CS)	-	
37	R001	N.M.	KOA	RK73B1JTTD101J	1/10W	
38	R002	N.M.	KOA	RK73B1JTTD101J	1/10W	
39	R003	N.M.	KOA	RK73B1JTTD101J	1/10W	
40	R004	N.M.	KOA	RK73B1JTTD101J	1/10W	
41	R005	N.M.	KOA	RK73B1JTTD101J	1/10W	
42	R006	N.M.	KOA	RK73B1JTTD101J	1/10W	
43	R007	N.M.	KOA	RK73B1JTTD101J	1/10W	
44	R008	N.M.	KOA	RK73B1JTTD101J	1/10W	
45	SW000		CoslandCo.,Ltd.	2MS1-T1-B4-M2-Q-E	-	
46	SW001		CoslandCo.,Ltd.	2MS1-T1-B4-M2-Q-E	-	
47	SW002		CoslandCo.,Ltd.	2MS1-T1-B4-M2-Q-E	-	
48	SW100	N.M.	Linkman	2130S1*40GSE	1A	
49	SW101	N.M.	Linkman	2130S1*40GSE	1A	

No.	Component number	Non-mounted	Vender	Part number	Rating	Note
50	SW102	N.M.	Linkman	2130S1*40GSE	1A	
51	SW103	N.M.	Linkman	2130S1*40GSE	1A	
52	TP001		Linkman	2130S1*40GSE	1A	
53	TP002		Linkman	2130S1*40GSE	1A	
54	TP003		Linkman	2130S1*40GSE	1A	
55	TP004		Linkman	2130S1*40GSE	1A	
56	TP005		Linkman	2130S1*40GSE	1A	
57	TP006		Linkman	2130S1*40GSE	1A	3×1 pin header
58	TP007		Linkman	2130S1*40GSE	1A	3×1 pin header
59	TP008		Linkman	2130S1*40GSE	1A	3×1 pin header
60	TP009		Linkman	2130S1*40GSE	1A	3×1 pin header
61	TP010		Linkman	2130S1*40GSE	1A	1 pin header
62	TP011		Linkman	2130S1*40GSE	1A	1 pin header
63	TP012		Linkman	2130S1*40GSE	1A	1 pin header
64	TP013		Linkman	2130S1*40GSE	1A	1 pin header
65	TP014		Linkman	2130S1*40GSE	1A	1 pin header
66	TP015		Linkman	2130S1*40GSE	1A	1 pin header
67	TP016		Linkman	2130S1*40GSE	1A	1 pin header
68	TP017		Linkman	2130S1*40GSE	1A	1 pin header
69	TP018		Linkman	2130S1*40GSE	1A	1 pin header
70	TP019		Linkman	2130S1*40GSE	1A	1 pin header
71	TP020		Linkman	2130S1*40GSE	1A	1 pin header
72	TP021		Linkman	2130S1*40GSE	1A	1 pin header
73	TP022		Linkman	2130S1*40GSE	1A	1 pin header
74	TP023		Linkman	2130S1*40GSE	1A	1 pin header
75	J001		Linkman	2130S1*40GSE	1A	1 pin header
76	J002		Linkman	2130S1*40GSE	1A	1 pin header
77	J003		Linkman	2130S1*40GSE	1A	1 pin header
78	D1		NXP Semicon.	PLVA662A	-	1 pin header
79	D2		NXP Semicon.	PLVA662A	-	1 pin header

These components are compliant with RoHS, but please ask each vender for details if necessary.

Figure 8-2. Picture (back)



9. Ordering Information



Table 9-1. Ordering Information

Part number	EVB revision	Note
MB39C811-EVB-02	Rev 1.0	---